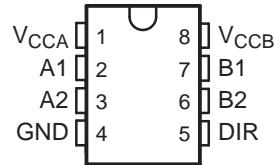
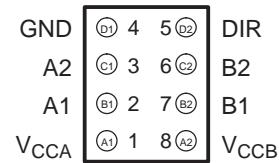


## FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Control Inputs  $V_{IH}/V_{IL}$  Levels Are Referenced to  $V_{CCA}$  Voltage
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.2-V to 3.6-V Power-Supply Range
- I/Os Are 4.6-V Tolerant
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Max Data Rates
  - 500 Mbps (1.8-V to 3.3-V Translation)
  - 320 Mbps (<1.8-V to 3.3-V Translation)
  - 320 Mbps (Translate to 2.5 V or 1.8 V)
  - 280 Mbps (Translate to 1.5 V)
  - 240 Mbps (Translate to 1.2 V)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 8000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

 DCT OR DCU PACKAGE  
 (TOP VIEW)

 YZP PACKAGE  
 (BOTTOM VIEW)


## DESCRIPTION/ORDERING INFORMATION

This dual-bit noninverting bus transceiver uses two separate configurable power-supply rails. The A port is designed to track  $V_{CCA}$ .  $V_{CCA}$  accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track  $V_{CCB}$ .  $V_{CCB}$  accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

### ORDERING INFORMATION

TA	PACKAGE <sup>(1)(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>
-40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74AVC2T45YZPR ____TD_
	SSOP – DCT	Reel of 3000	SN74AVC2T45DCTR DT2_ __
	VSSOP – DCU	Reel of 3000	SN74AVC2T45DCUR DT2_

- Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).
- For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).
- DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.  
 DCU: The actual top-side marking has one additional character that designates the assembly/test site.  
 YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

## DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The SN74AVC2T45 is designed for asynchronous communication between two data buses. The logic levels of the direction-control (DIR) input activate either the B-port outputs or the A-port outputs. The device transmits data from the A bus to the B bus when the B-port outputs are activated and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports always is active and must have a logic HIGH or LOW level applied to prevent excess  $I_{CC}$  and  $I_{CCZ}$ .

The SN74AVC2T45 is designed so that the DIR input is powered by  $V_{CCA}$ .

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The  $V_{CC}$  isolation feature ensures that if either  $V_{CC}$  input is at GND, both ports are in the high-impedance state.

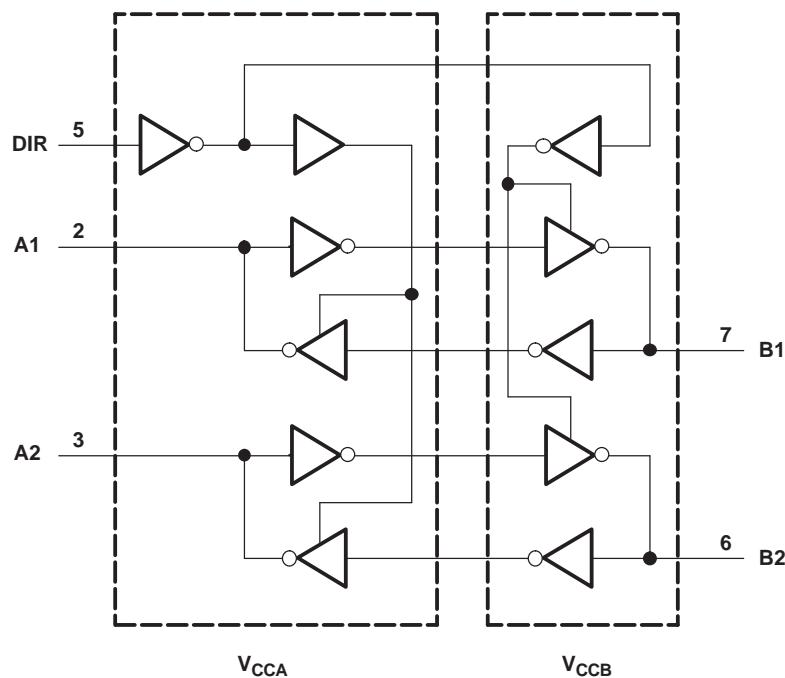
NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

**FUNCTION TABLE<sup>(1)</sup>  
(EACH TRANSCEIVER)**

INPUT DIR	OPERATION
L	B data to A bus
H	A data to B bus

(1) Input circuits of the data I/Os always are active.

**LOGIC DIAGRAM (POSITIVE LOGIC)<sup>(1)</sup>**



(1) Pin numbers are for the DCT and DCU packages only.

**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CCA}$	Supply voltage range	-0.5	4.6	V
$V_I$	Input voltage range <sup>(2)</sup>	I/O ports (A port)	-0.5	4.6
		I/O ports (B port)	-0.5	4.6
		Control inputs	-0.5	4.6
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	A port	-0.5	4.6
		B port	-0.5	4.6
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	A port	-0.5	$V_{CCA} + 0.5$
		B port	-0.5	$V_{CCB} + 0.5$
$I_{IK}$	Input clamp current	$V_I < 0$	-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$	-50	mA
$I_O$	Continuous output current		$\pm 50$	mA
Continuous current through $V_{CCA}$ , $V_{CCB}$ , or GND			$\pm 100$	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DCT package	220	°C/W
		DCU package	227	
		YZP package	102	
$T_{stg}$	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current ratings are observed.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions<sup>(1)(2)(3)(4)(5)</sup>

		V <sub>CCI</sub>	V <sub>CCO</sub>	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage			1.2	3.6	V
V <sub>CCB</sub>	Supply voltage			1.2	3.6	V
V <sub>IH</sub>	High-level input voltage	Data inputs <sup>(4)</sup>	1.2 V to 1.95 V	V <sub>CCI</sub> × 0.65	2	V
			1.95 V to 2.7 V	1.6		
			2.7 V to 3.6 V	2		
V <sub>IL</sub>	Low-level input voltage	Data inputs <sup>(4)</sup>	1.2 V to 1.95 V	V <sub>CCI</sub> × 0.35	0.8	V
			1.95 V to 2.7 V	0.7		
			2.7 V to 3.6 V	0.8		
V <sub>IH</sub>	High-level input voltage	DIR (referenced to V <sub>CCA</sub> ) <sup>(5)</sup>	1.2 V to 1.95 V	V <sub>CCA</sub> × 0.65	2	V
			1.95 V to 2.7 V	1.6		
			2.7 V to 3.6 V	2		
V <sub>IL</sub>	Low-level input voltage	DIR (referenced to V <sub>CCA</sub> ) <sup>(5)</sup>	1.2 V to 1.95 V	V <sub>CCA</sub> × 0.35	0.8	V
			1.95 V to 2.7 V	0.7		
			2.7 V to 3.6 V	0.8		
V <sub>I</sub>	Input voltage			0	3.6	V
V <sub>O</sub>	Output voltage	Active state		0	V <sub>CCO</sub>	V
		3-state		0	3.6	
I <sub>OH</sub>	High-level output current		1.2 V		-3	mA
			1.4 V to 1.6 V		-6	
			1.65 V to 1.95 V		-8	
			2.3 V to 2.7 V		-9	
			3 V to 3.6 V		-12	
I <sub>OL</sub>	Low-level output current		1.2 V		3	mA
			1.4 V to 1.6 V		6	
			1.65 V to 1.95 V		8	
			2.3 V to 2.7 V		9	
			3 V to 3.6 V		12	
Δt/Δv	Input transition rise or fall rate				5	ns/V
T <sub>A</sub>	Operating free-air temperature			-40	85	°C

(1) V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.(2) V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.(3) All unused data inputs of the device must be held at V<sub>CCI</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.(4) For V<sub>CCI</sub> values not specified in the data sheet, V<sub>IH</sub> min = V<sub>CCI</sub> × 0.7 V, V<sub>IL</sub> max = V<sub>CCI</sub> × 0.3 V.(5) For V<sub>CCI</sub> values not specified in the data sheet, V<sub>IH</sub> min = V<sub>CCA</sub> × 0.7 V, V<sub>IL</sub> max = V<sub>CCA</sub> × 0.3 V.

**Electrical Characteristics<sup>(1)(2)</sup>**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			-40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -100 µA	V <sub>I</sub> = V <sub>IH</sub>	1.2 V to 3.6 V	1.2 V to 3.6 V			V <sub>CCO</sub> - 0.2 V		V
	I <sub>OH</sub> = -3 mA		1.2 V	1.2 V	0.95				
	I <sub>OH</sub> = -6 mA		1.4 V	1.4 V			1.05		
	I <sub>OH</sub> = -8 mA		1.65 V	1.65 V			1.2		
	I <sub>OH</sub> = -9 mA		2.3 V	2.3 V			1.75		
	I <sub>OH</sub> = -12 mA		3 V	3 V			2.3		
V <sub>OL</sub>	I <sub>OL</sub> = 100 µA	V <sub>I</sub> = V <sub>IL</sub>	1.2 V to 3.6 V	1.2 V to 3.6 V			0.2		V
	I <sub>OL</sub> = 3 mA		1.2 V	1.2 V	0.25				
	I <sub>OL</sub> = 6 mA		1.4 V	1.4 V			0.35		
	I <sub>OL</sub> = 8 mA		1.65 V	1.65 V			0.45		
	I <sub>OL</sub> = 9 mA		2.3 V	2.3 V			0.55		
	I <sub>OL</sub> = 12 mA		3 V	3 V			0.7		
I <sub>I</sub>	DIR	V <sub>I</sub> = V <sub>CCA</sub> or GND	1.2 V to 3.6 V	1.2 V to 3.6 V	±0.025	±0.25		±1	µA
I <sub>off</sub>	A port	V <sub>I</sub> or V <sub>O</sub> = 0 to 3.6 V	0 V	0 to 3.6 V	±0.1	±1		±5	µA
	B port		0 to 3.6 V	0 V	±0.1	±1		±5	
I <sub>OZ</sub>	B port	V <sub>O</sub> = V <sub>CCO</sub> or GND	0 V	3.6 V	±0.5	±2.5		±5	µA
	A port	V <sub>I</sub> = V <sub>CCI</sub> or GND	3.6 V	0 V	±0.5	±2.5		±5	
I <sub>CCA</sub>	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2 V to 3.6 V	1.2 V to 3.6 V				10		µA
		0 V	3.6 V				-2		
		3.6 V	0 V				10		
I <sub>CCB</sub>	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2 V to 3.6 V	1.2 V to 3.6 V				10		µA
		0 V	3.6 V				10		
		3.6 V	0 V				-2		
I <sub>CCA</sub> + I <sub>CCB</sub> (see Table 1)	V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2 V to 3.6 V	1.2 V to 3.6 V				20		µA
C <sub>I</sub>	Control inputs	V <sub>I</sub> = 3.3 V or GND	3.3 V	3.3 V	2.5				pF
C <sub>io</sub>	A or B port	V <sub>O</sub> = 3.3 V or GND	3.3 V	3.3 V	6				pF

 (1) V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.

 (2) V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 1.2\text{ V}$  (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2\text{ V}$	$V_{CCB} = 1.5\text{ V}$	$V_{CCB} = 1.8\text{ V}$	$V_{CCB} = 2.5\text{ V}$	$V_{CCB} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	TYP	TYP	
$t_{PLH}$	A	B	3.1	2.6	2.4	2.2	2.2	ns
$t_{PHL}$			3.1	2.6	2.4	2.2	2.2	
$t_{PLH}$	B	A	3.4	3.1	3	2.9	2.9	ns
$t_{PHL}$			3.4	3.1	3	2.9	2.9	
$t_{PHZ}$	DIR	A	5.2	5.2	5.1	5	4.8	ns
$t_{PLZ}$			5.2	5.2	5.1	5	4.8	
$t_{PHZ}$	DIR	B	5	4	3.8	2.8	3.2	ns
$t_{PLZ}$			5	4	3.8	2.8	3.2	
$t_{PZH}^{(1)}$	DIR	A	8.4	7.1	6.8	5.7	6.1	ns
$t_{PZL}^{(1)}$			8.4	7.1	6.8	5.7	6.1	
$t_{PZH}^{(1)}$	DIR	B	8.3	7.8	7.5	7.2	7	ns
$t_{PZL}^{(1)}$			8.3	7.8	7.5	7.2	7	

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$  (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2\text{ V}$	$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	UNIT	
			TYP	MIN	MAX	MIN	MAX		
$t_{PLH}$	A	B	2.8	0.7	5.4	0.5	4.6	0.4 3.7 0.3 3.5	ns
$t_{PHL}$			2.8	0.7	5.4	0.5	4.6	0.4 3.7 0.3 3.5	
$t_{PLH}$	B	A	2.7	0.8	5.4	0.7	5.2	0.6 4.9 0.5 4.7	ns
$t_{PHL}$			2.7	0.8	5.4	0.7	5.2	0.6 4.9 0.5 4.7	
$t_{PHZ}$	DIR	A	3.9	1.3	8.5	1.3	7.8	1.1 7.7 1.4 7.6	ns
$t_{PLZ}$			3.9	1.3	8.5	1.3	7.8	1.1 7.7 1.4 7.6	
$t_{PHZ}$	DIR	B	4.7	1.1	7	1.4	6.9	1.2 6.9 1.7 7.1	ns
$t_{PLZ}$			4.7	1.1	7	1.4	6.9	1.2 6.9 1.7 7.1	
$t_{PZH}^{(1)}$	DIR	A	7.4		12.4		12.1	11.8	ns
$t_{PZL}^{(1)}$			7.4		12.4		12.1	11.8	
$t_{PZH}^{(1)}$	DIR	B	6.7		13.9		12.4	11.4	ns
$t_{PZL}^{(1)}$			6.7		13.9		12.4	11.4	

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$  (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2 \text{ V}$	$V_{CCB} = 1.5 \text{ V} \pm 0.1 \text{ V}$		$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	2.7	0.5	5.2	0.4	4.3	0.2	3.4	0.2	3.1	ns
$t_{PHL}$			2.7	0.5	5.2	0.4	4.3	0.2	3.4	0.2	3.1	
$t_{PLH}$	B	A	2.4	0.7	4.7	0.5	4.4	0.5	4	0.4	3.8	ns
$t_{PHL}$			2.4	0.7	4.7	0.5	4.4	0.5	4	0.4	3.8	
$t_{PHZ}$	DIR	A	3.7	1.3	8.1	0.7	6.9	1.4	5.3	1.1	5.2	ns
$t_{PLZ}$			3.7	1.3	8.1	0.7	6.9	1.4	5.3	1.1	5.2	
$t_{PHZ}$	DIR	B	4.4	1.3	5.8	1.3	5.9	0.8	5.7	1.5	5.9	ns
$t_{PLZ}$			4.4	1.3	5.8	1.3	5.9	0.8	5.7	1.5	5.9	
$t_{PZH}^{(1)}$	DIR	A	6.8		10.5		10.3		9.7		9.7	ns
$t_{PZL}^{(1)}$			6.8		10.5		10.3		9.7		9.7	
$t_{PZH}^{(1)}$	DIR	B	6.4		13.3		11.2		8.7		8.3	ns
$t_{PZL}^{(1)}$			6.4		13.3		11.2		8.7		8.3	

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$  (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2 \text{ V}$	$V_{CCB} = 1.5 \text{ V} \pm 0.1 \text{ V}$		$V_{CCB} = 1.8 \text{ V} \pm 0.15 \text{ V}$		$V_{CCB} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CCB} = 3.3 \text{ V} \pm 0.3 \text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	2.6	0.4	4.9	0.2	4	0.2	3	0.2	2.6	ns
$t_{PHL}$			2.6	0.4	4.9	0.2	4	0.2	3	0.2	2.6	
$t_{PLH}$	B	A	2.1	0.6	3.8	0.5	3.4	0.4	3	0.3	2.8	ns
$t_{PHL}$			2.1	0.6	3.8	0.5	3.4	0.4	3	0.3	2.8	
$t_{PHZ}$	DIR	A	2.4	0.7	7.9	0.8	6.4	0.8	5	0.5	4.3	ns
$t_{PLZ}$			2.4	0.7	7.9	0.8	6.4	0.8	5	0.5	4.3	
$t_{PHZ}$	DIR	B	3.8	1	4.3	0.6	4.3	0.5	4.2	1.1	4.1	ns
$t_{PLZ}$			3.8	1	4.3	0.6	4.3	0.5	4.2	1.1	4.1	
$t_{PZH}^{(1)}$	DIR	A	5.9		8.5		7.7		7.2		6.9	ns
$t_{PZL}^{(1)}$			5.9		8.5		7.7		7.2		6.9	
$t_{PZH}^{(1)}$	DIR	B	5		12.8		10.4		8		6.9	ns
$t_{PZL}^{(1)}$			5		12.8		10.4		8		6.9	

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$  (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.2\text{ V}$	$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$		$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	B	2.5	0.3	4.7	0.2	3.8	0.2	2.8	0.2	2.4	ns
$t_{PHL}$			2.5	0.3	4.7	0.2	3.8	0.2	2.8	0.2	2.4	
$t_{PLH}$	B	A	2.1	0.6	3.6	0.4	3.1	0.3	2.6	0.3	2.4	ns
$t_{PHL}$			2.1	0.6	3.6	0.4	3.1	0.3	2.6	0.3	2.4	
$t_{PHZ}$	DIR	A	2.9	1.1	8	1	6.5	1.3	4.7	1.2	4	ns
$t_{PLZ}$			2.9	1.1	8	1	6.5	1.3	4.7	1.2	4	
$t_{PHZ}$	DIR	B	3.4	0.5	6.6	0.3	5.6	0.3	4.6	1.1	4.2	ns
$t_{PLZ}$			3.4	0.5	6.6	0.3	5.6	0.3	4.6	1.1	4.2	
$t_{PZH}^{(1)}$	DIR	A	5.5		10.2		8.7		7.2		6.6	ns
$t_{PZL}^{(1)}$			5.5		10.2		8.7		7.2		6.6	
$t_{PZH}^{(1)}$	DIR	B	5.4		12.7		10.3		7.5		6.4	ns
$t_{PZL}^{(1)}$			5.4		12.7		10.3		7.5		6.4	

(1) The enable time is a calculated value, derived using the formula shown in the *enable times* section.

## Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CCA} =$ $V_{CCB} = 1.2\text{ V}$	$V_{CCA} =$ $V_{CCB} = 1.5\text{ V}$	$V_{CCA} =$ $V_{CCB} = 1.8\text{ V}$	$V_{CCA} =$ $V_{CCB} = 2.5\text{ V}$	$V_{CCA} =$ $V_{CCB} = 3.3\text{ V}$	UNIT	
		TYP	TYP	TYP	TYP	TYP		
$C_{pdA}^{(1)}$	A-port input, B-port output	$C_L = 0$ , $f = 10\text{ MHz}$ , $t_r = t_f = 1\text{ ns}$	3	3	3	3	4	pF
	B-port input, A-port output		12	13	13	14	15	
$C_{pdB}^{(1)}$	A-port input, B-port output	$C_L = 0$ , $f = 10\text{ MHz}$ , $t_r = t_f = 1\text{ ns}$	12	13	13	14	15	pF
	B-port input, A-port output		3	3	3	3	4	

(1) Power-dissipation capacitance per transceiver

### Power-Up Considerations

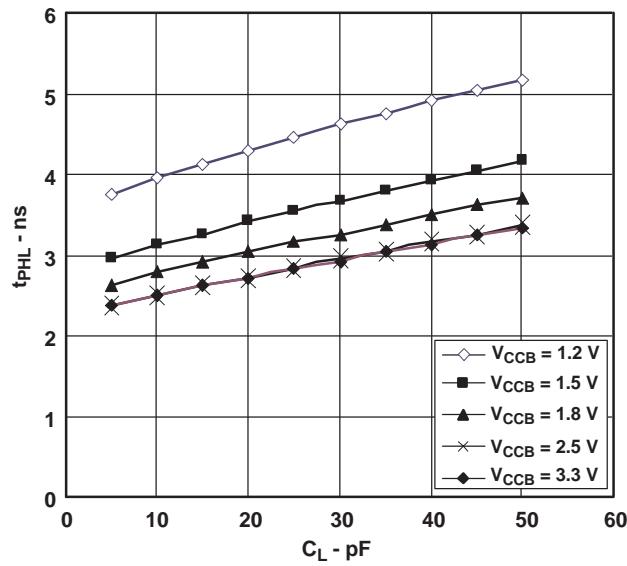
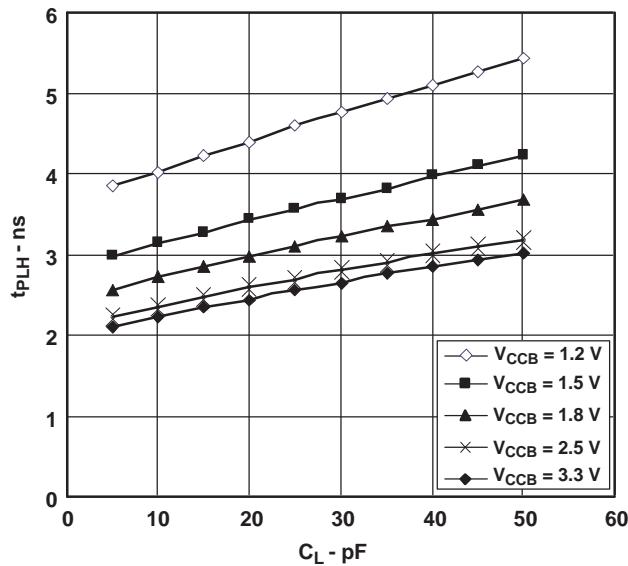
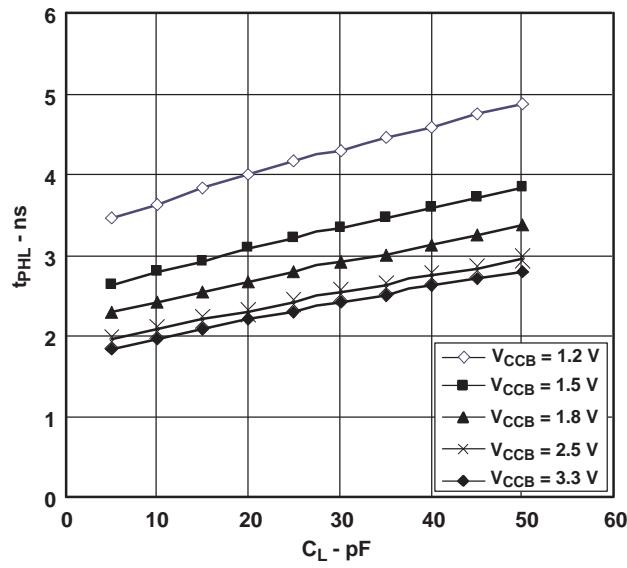
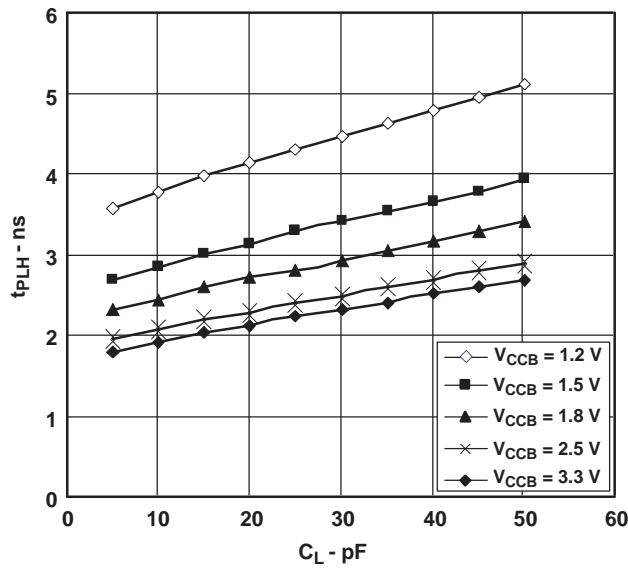
A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies. To guard against such power-up problems, take the following precautions:

1. Connect ground before any supply voltage is applied.
2. Power up  $V_{CCA}$ .
3.  $V_{CCB}$  can be ramped up along with or after  $V_{CCA}$ .

**Table 1. Typical Total Static Power Consumption ( $I_{CCA} + I_{CCB}$ )**

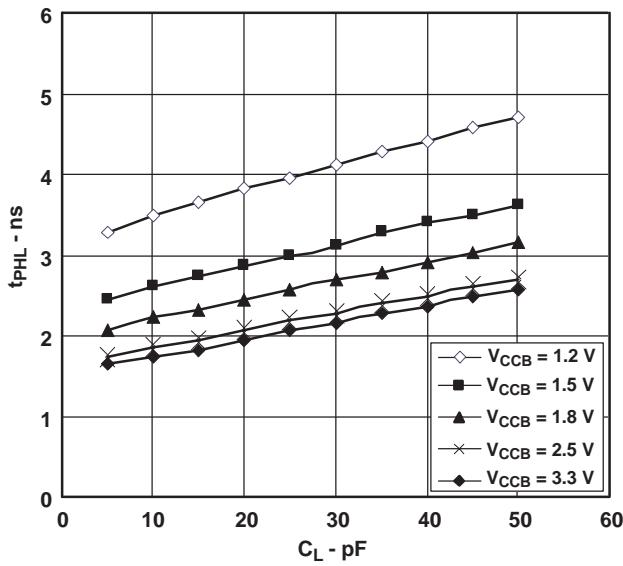
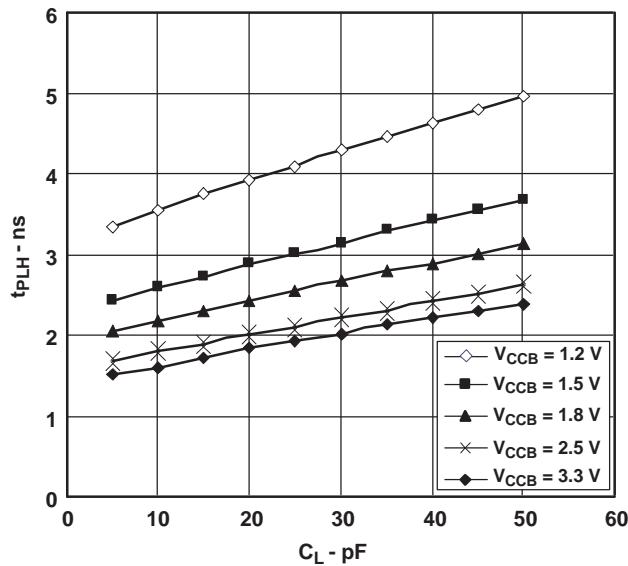
$V_{CCB}$	$V_{CCA}$						<b>UNIT</b>
	<b>0 V</b>	<b>1.2 V</b>	<b>1.5 V</b>	<b>1.8 V</b>	<b>2.5 V</b>	<b>3.3 V</b>	
<b>0 V</b>	0	<0.5	<0.5	<0.5	<0.5	<0.5	
<b>1.2 V</b>	<0.5	<1	<1	<1	<1	1	
<b>1.5 V</b>	<0.5	<1	<1	<1	<1	1	
<b>1.8 V</b>	<0.5	<1	<1	<1	<1	<1	
<b>2.5 V</b>	<0.5	1	<1	<1	<1	<1	
<b>3.3 V</b>	<0.5	1	<1	<1	<1	<1	

## TYPICAL CHARACTERISTICS

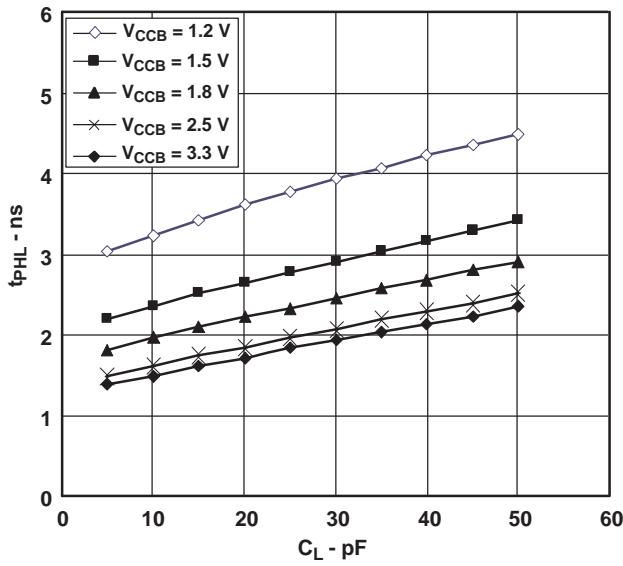
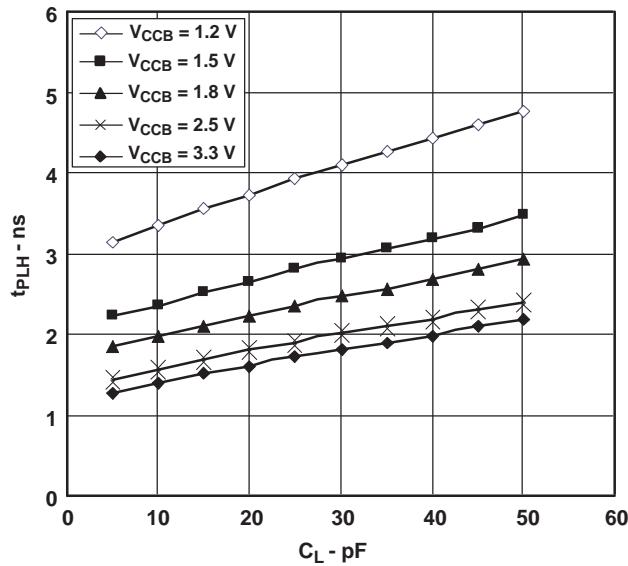
TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE,  
 $T_A = 25^\circ\text{C}$ ,  $V_{CCA} = 1.2\text{ V}$ TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE,  
 $T_A = 25^\circ\text{C}$ ,  $V_{CCA} = 1.5\text{ V}$ 

## TYPICAL CHARACTERISTICS

**TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE,  
 $T_A = 25^\circ\text{C}$ ,  $V_{CCA} = 1.8\text{ V}$**

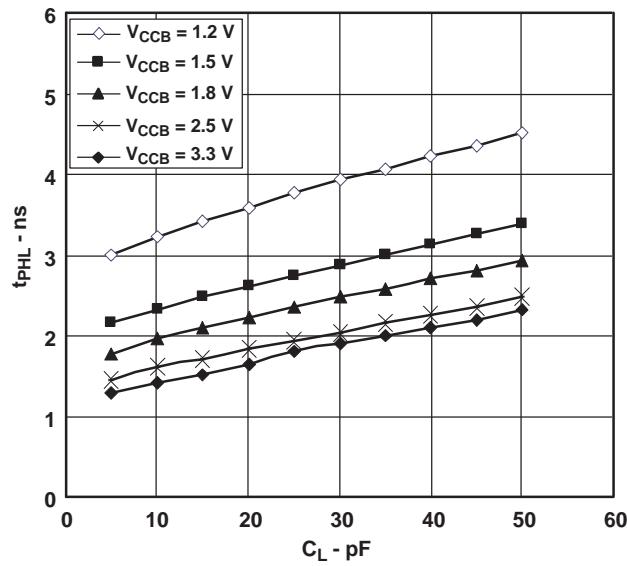
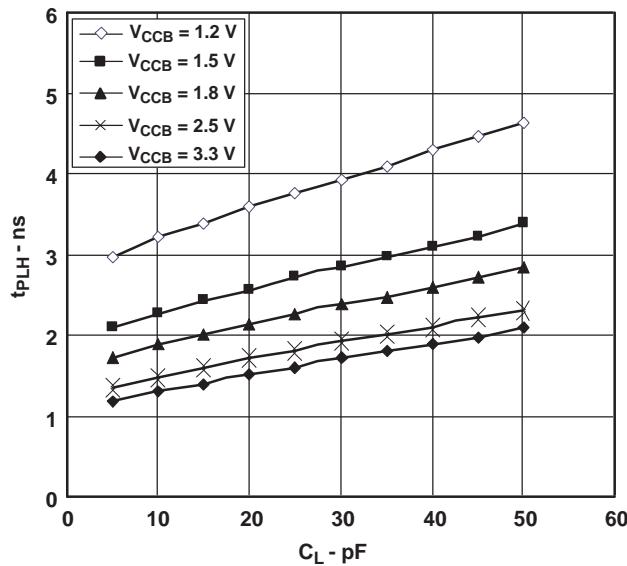


**TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE,  
 $T_A = 25^\circ\text{C}$ ,  $V_{CCA} = 2.5\text{ V}$**

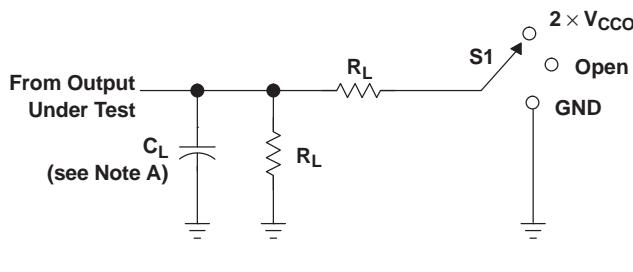


### TYPICAL CHARACTERISTICS

**TYPICAL PROPAGATION DELAY (A to B) vs LOAD CAPACITANCE,  
 $T_A = 25^\circ\text{C}$ ,  $V_{CCA} = 3.3\text{ V}$**

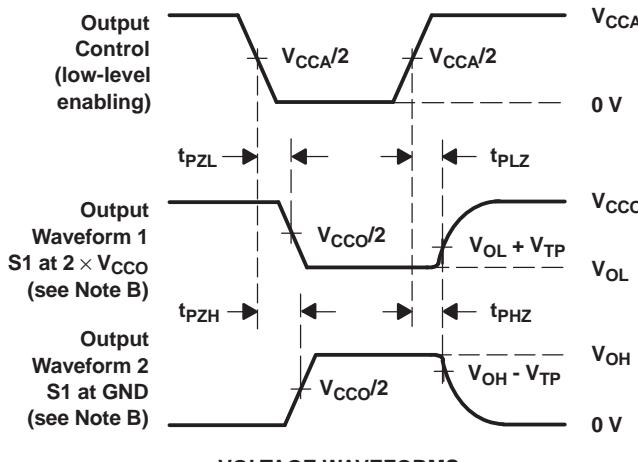
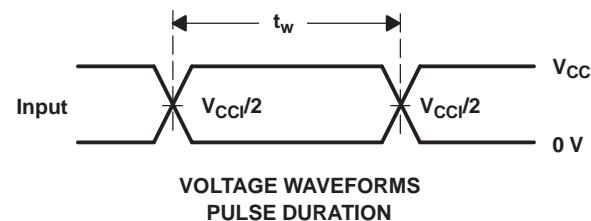
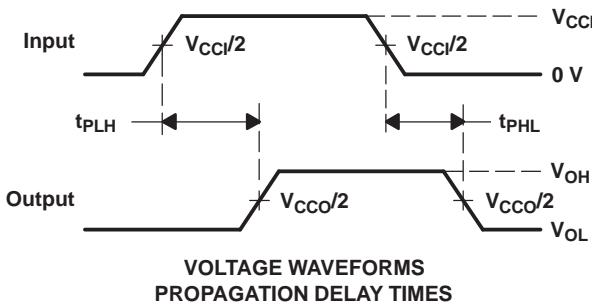


PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CCO}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CCO}$	$C_L$	$R_L$	$V_{TP}$
1.2 V	15 pF	2 k $\Omega$	0.1 V
$1.5 V \pm 0.1 V$	15 pF	2 k $\Omega$	0.1 V
$1.8 V \pm 0.15 V$	15 pF	2 k $\Omega$	0.15 V
$2.5 V \pm 0.2 V$	15 pF	2 k $\Omega$	0.15 V
$3.3 V \pm 0.3 V$	15 pF	2 k $\Omega$	0.3 V

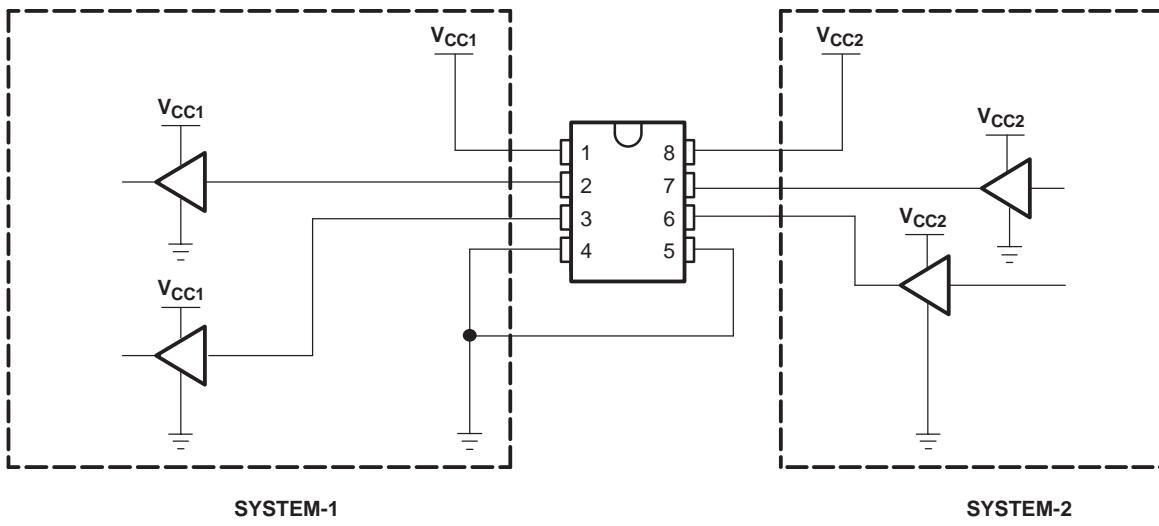


NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50 \Omega$ ,  $dv/dt \geq 1$  V/ns.  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{pd}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H.  $V_{CCl}$  is the  $V_{CC}$  associated with the input port.  
 I.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

Figure 1. Load Circuit and Voltage Waveforms

## APPLICATION INFORMATION

Figure 2 is an example circuit of the SN74AVC2T45 used in a unidirectional logic level-shifting application.

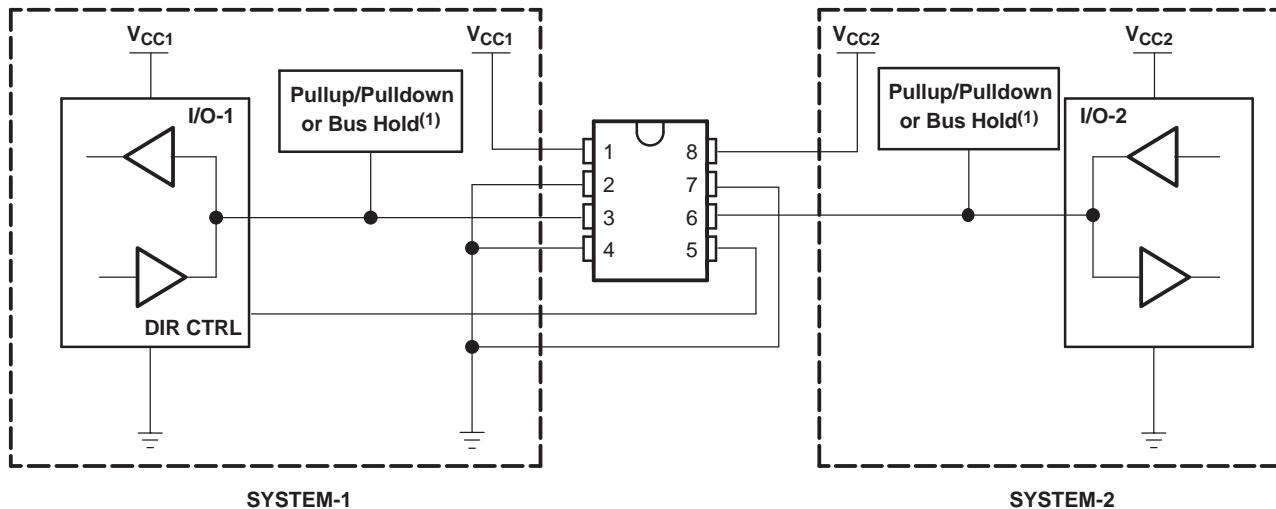


PIN	NAME	FUNCTION	DESCRIPTION
1	V <sub>CCA</sub>	V <sub>CC1</sub>	SYSTEM-1 supply voltage (1.2 V to 3.6 V)
2	A1	OUT1	Output level depends on V <sub>CC1</sub> voltage.
3	A2	OUT2	Output level depends on V <sub>CC1</sub> voltage.
4	GND	GND	Device GND
5	DIR	DIR	The GND (low-level) determines B-port to A-port direction.
6	B2	IN2	Input threshold value depends on V <sub>CC2</sub> voltage.
7	B1	IN1	Input threshold value depends on V <sub>CC2</sub> voltage.
8	V <sub>CCB</sub>	V <sub>CC2</sub>	SYSTEM-2 supply voltage (1.2 V to 3.6 V)

**Figure 2. Unidirectional Logic Level-Shifting Application**

## APPLICATION INFORMATION

Figure 3 shows the SN74AVC2T45 used in a bidirectional logic level-shifting application. Since the SN74AVC2T45 does not have an output-enable (OE) pin, the system designer should take precautions to avoid bus contention between SYSTEM-1 and SYSTEM-2 when changing directions.



Following is a sequence that illustrates data transmission from SYSTEM-1 to SYSTEM-2 and then from SYSTEM-2 to SYSTEM-1.

STATE	DIR CTRL	I/O-1	I/O-2	DESCRIPTION
1	H	Out	In	SYSTEM-1 data to SYSTEM-2
2	H	Hi-Z	Hi-Z	SYSTEM-2 is getting ready to send data to SYSTEM-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on pullup or pulldown. <sup>(1)</sup>
3	L	Hi-Z	Hi-Z	DIR bit is flipped. I/O-1 and I/O-2 still are disabled. The bus-line state depends on pullup or pulldown. <sup>(1)</sup>
4	L	In	Out	SYSTEM-2 data to SYSTEM-1

(1) SYSTEM-1 and SYSTEM-2 must use the same conditions, i.e., both pullup or both pulldown.

**Figure 3. Bidirectional Logic Level-Shifting Application**

### Enable Times

Calculate the enable times for the SN74AVC2T45 using the following formulas:

- $t_{PZH}$  (DIR to A) =  $t_{PLZ}$  (DIR to B) +  $t_{PLH}$  (B to A)
- $t_{PZL}$  (DIR to A) =  $t_{PHZ}$  (DIR to B) +  $t_{PHL}$  (B to A)
- $t_{PZH}$  (DIR to B) =  $t_{PLZ}$  (DIR to A) +  $t_{PLH}$  (A to B)
- $t_{PZL}$  (DIR to B) =  $t_{PHZ}$  (DIR to A) +  $t_{PHL}$  (A to B)

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the SN74AVC2T45 initially is transmitting from A to B, then the DIR bit is switched; the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AVC2T45DCTR	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DT2Z	Samples
SN74AVC2T45DCTRE4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DT2Z	Samples
SN74AVC2T45DCTT	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DT2Z	Samples
SN74AVC2T45DCTTG4	ACTIVE	SM8	DCT	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DT2Z	Samples
SN74AVC2T45DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU   CU SN	Level-1-260C-UNLIM	-40 to 85	(DT2R ~ T2) DZ	Samples
SN74AVC2T45DCURE4	ACTIVE	US8	DCU	8		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AVC2T45DCURG4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DT2R	Samples
SN74AVC2T45DCUT	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DT2R	Samples
SN74AVC2T45DCUTE4	ACTIVE	US8	DCU	8		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AVC2T45DCUTG4	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	DT2R	Samples
SN74AVC2T45YZPR	ACTIVE	DSBGA	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(TD7 ~ TDN)	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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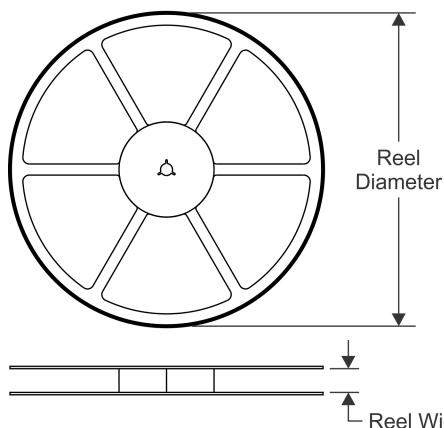
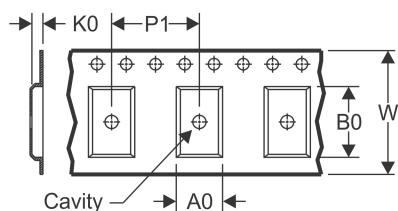
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN74AVC2T45 :**

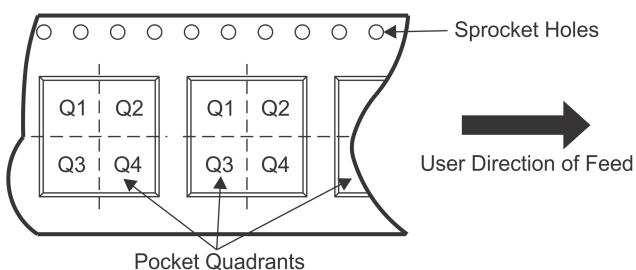
- Automotive: [SN74AVC2T45-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

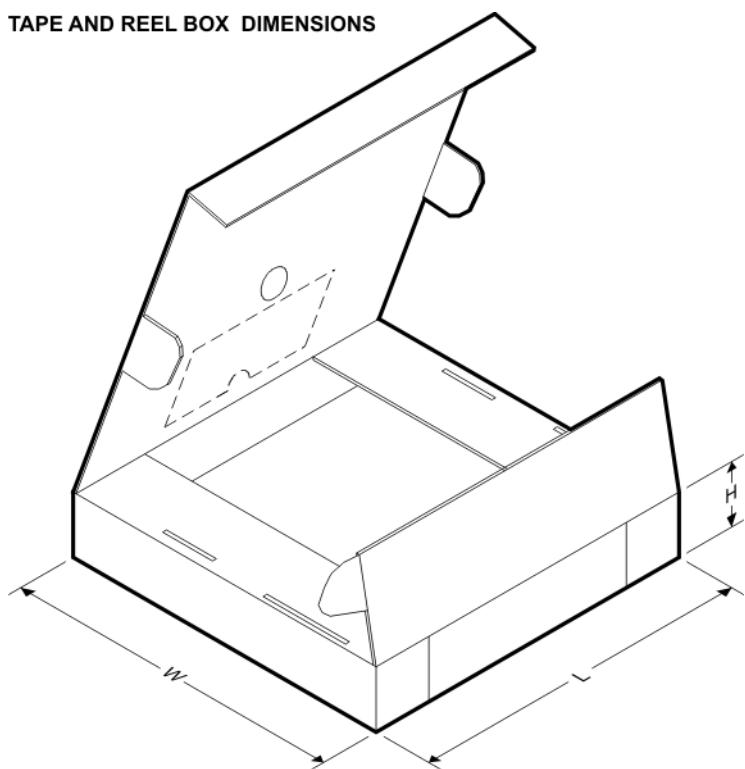
**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVC2T45DCUR	US8	DCU	8	3000	180.0	9.0	2.05	3.3	1.0	4.0	8.0	Q3
SN74AVC2T45DCUR	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AVC2T45DCURG4	US8	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AVC2T45DCUTG4	US8	DCU	8	250	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
SN74AVC2T45YZPR	DSBGA	YZP	8	3000	178.0	9.2	1.02	2.02	0.63	4.0	8.0	Q1

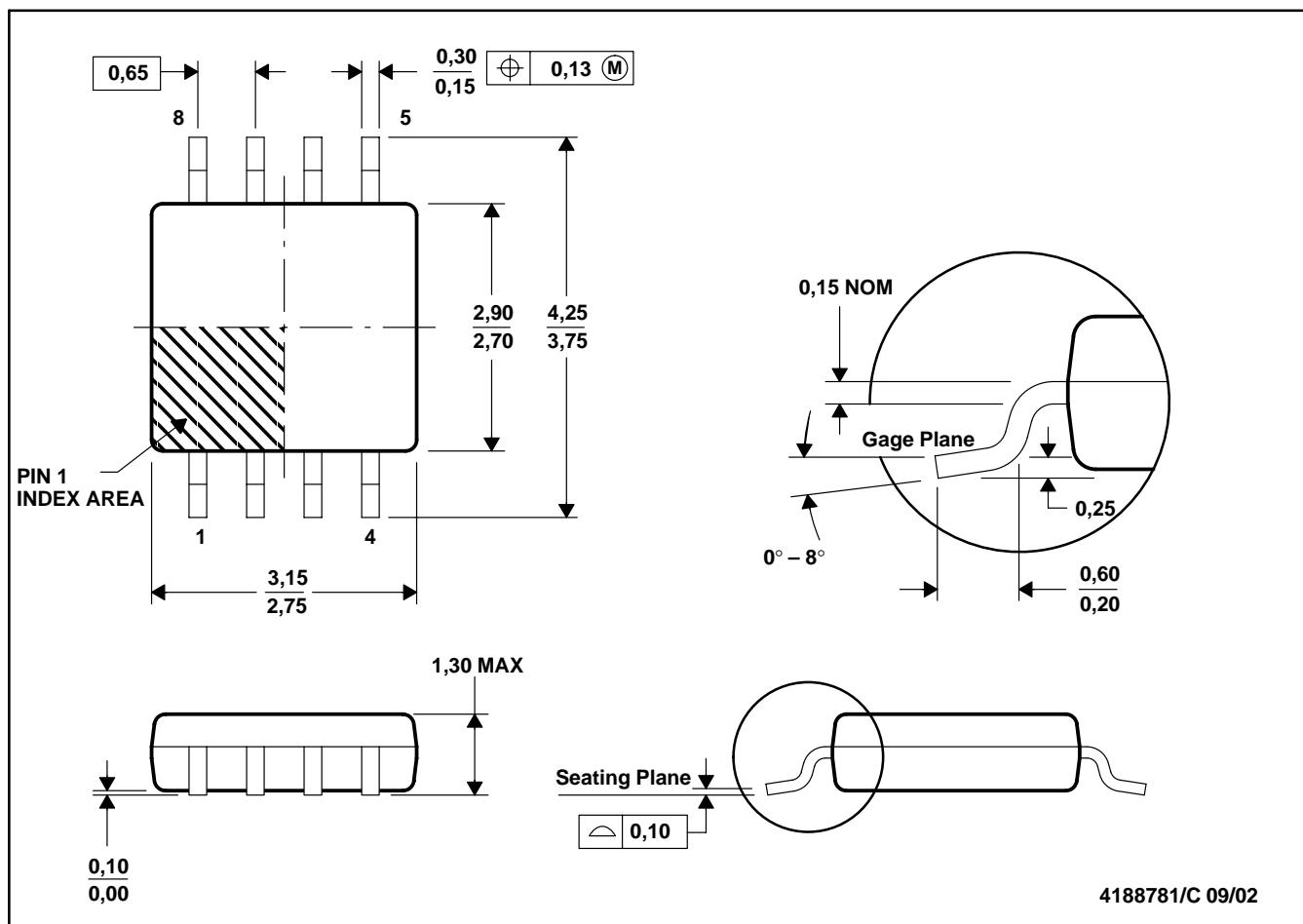
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVC2T45DCUR	US8	DCU	8	3000	182.0	182.0	20.0
SN74AVC2T45DCUR	US8	DCU	8	3000	202.0	201.0	28.0
SN74AVC2T45DCURG4	US8	DCU	8	3000	202.0	201.0	28.0
SN74AVC2T45DCUTG4	US8	DCU	8	250	202.0	201.0	28.0
SN74AVC2T45YZPR	DSBGA	YZP	8	3000	220.0	220.0	35.0

## DCT (R-PDSO-G8)

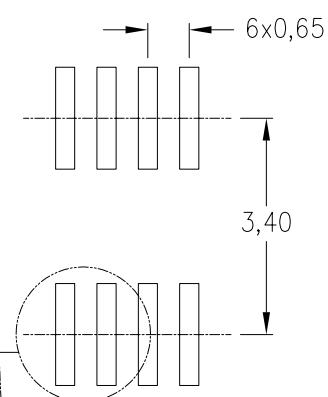
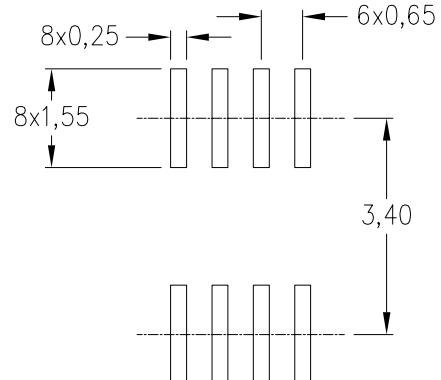
## PLASTIC SMALL-OUTLINE PACKAGE



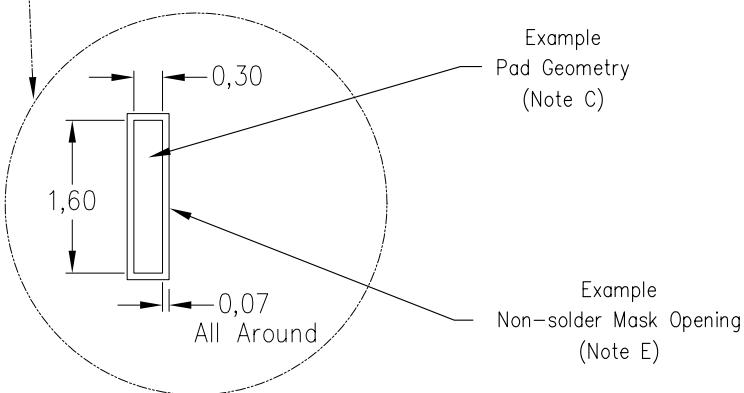
NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion  
 D. Falls within JEDEC MO-187 variation DA.

DCT (R-PDSO-G8)

PLASTIC SMALL OUTLINE

Example Board Layout  
(Note C,E)Example Stencil Design  
(Note D)

Non Solder Mask Defined Pad

Example  
Pad Geometry  
(Note C)Example  
Non-solder Mask Opening  
(Note E)

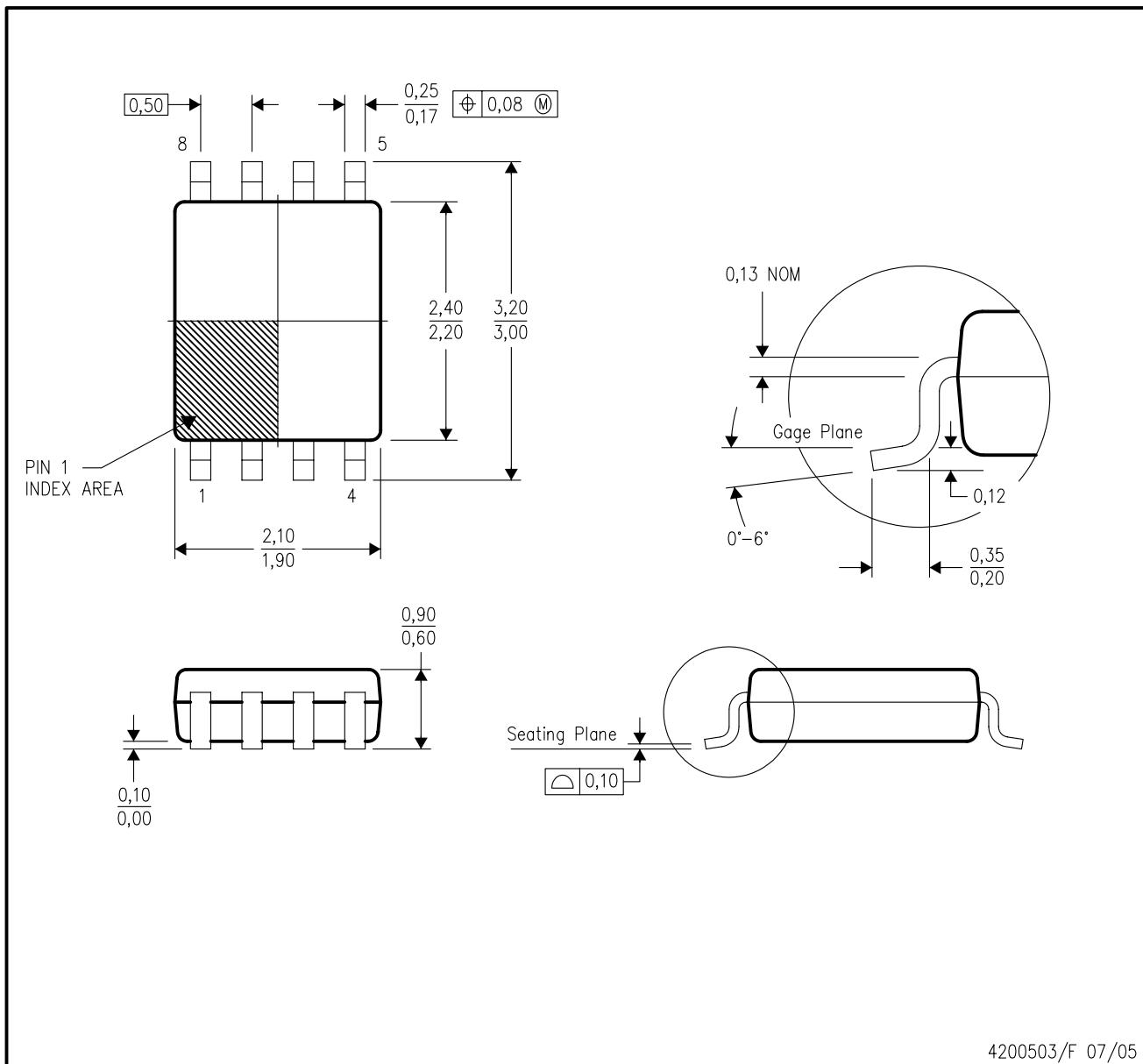
4212201/A 10/11

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## DCU (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



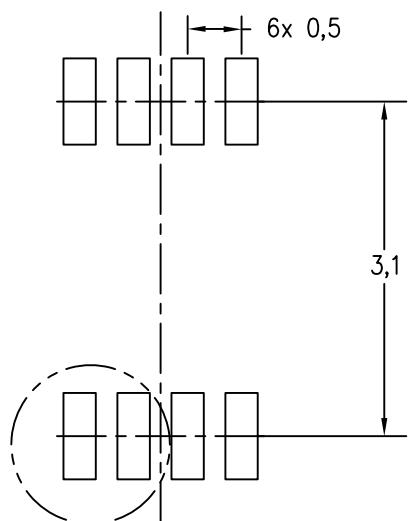
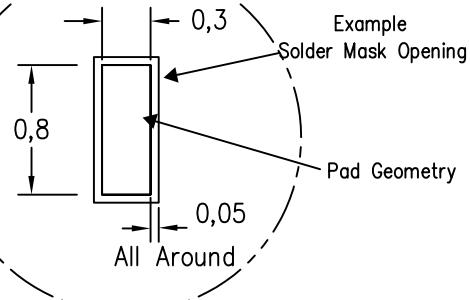
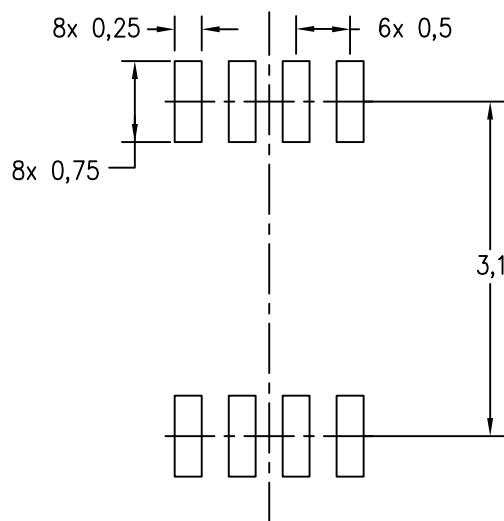
4200503/F 07/05

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-187 variation CA.

DCU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)

Example Board Layout  
(Note C,E)Example Stencil Design  
(Note D)

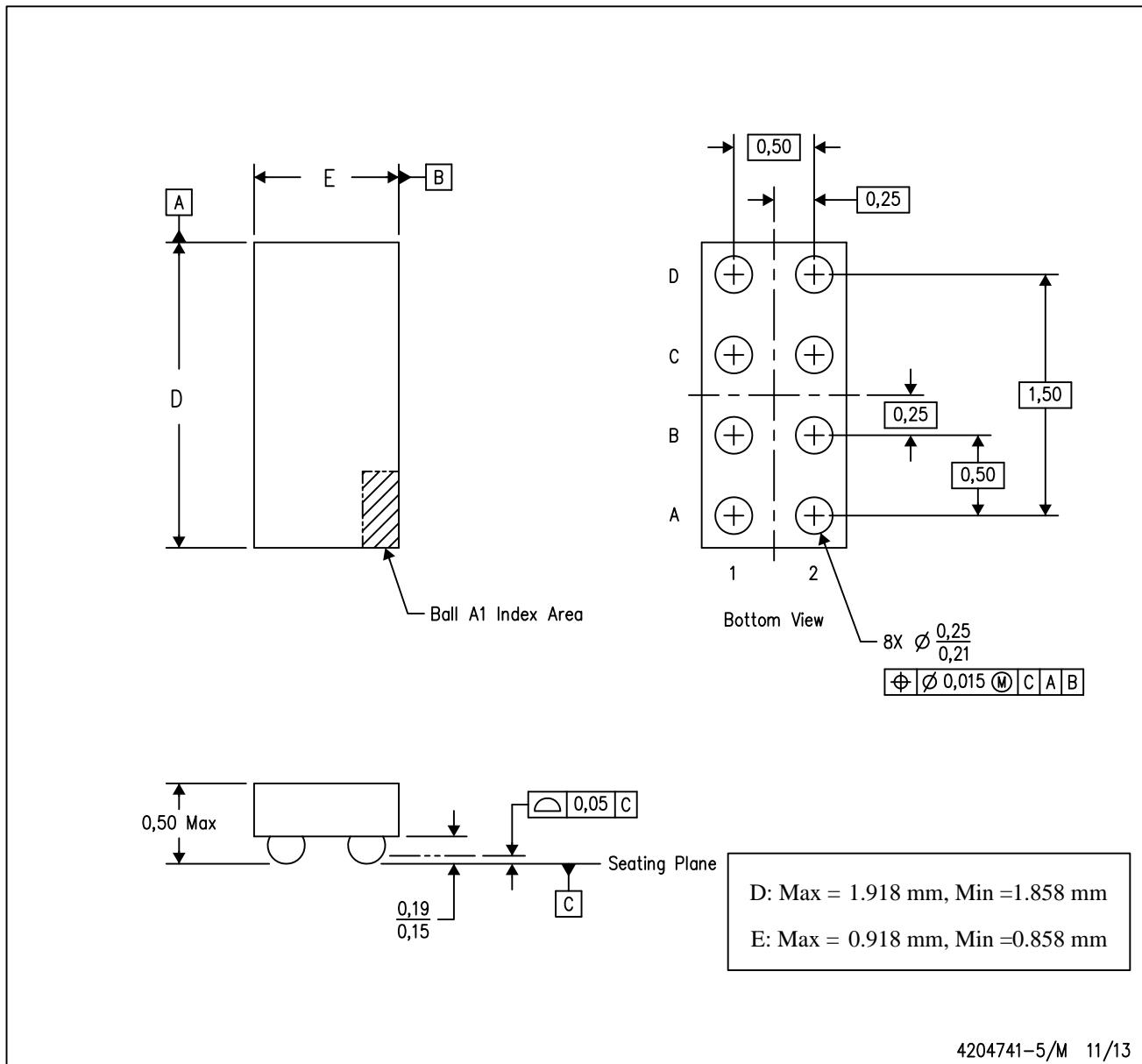
4210064/C 04/12

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

YZP (R-XBGA-N8)

DIE-SIZE BALL GRID ARRAY



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